

Amendments to the Claims

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims

Claim 1. (currently amended) An arrangement for use in a package, comprising:

- a supporting substrate with a bond opening therein;
- an interconnect layer on the supporting substrate, in which a bonding channel overlapping with the bond opening is formed;
- a chip fixed to the interconnect layer to cover the bonding channel;
- at least one wire connected to the chip and extending through the bond opening and the bonding channel;
- an encapsulation material arranged in the bonding channel; and
- an escape prevention structure for the bonding channel, to enable escaping of air from the bonding channel and to substantially prevent the encapsulation material from escaping from the bonding channel.

Claim 2. (previously presented) The arrangement of claim 1, wherein the escape prevention structure is designed to prevent escaping of the encapsulation material due to the capillary effect.

Claim 3. (previously presented) The arrangement of claim 1, wherein the escape prevention structure includes an opening with such a cross-sectional area, so that escaping of the encapsulation material caused by the capillary effect is prevented.

Claim 4. (previously presented) The arrangement of claim 1, wherein the bonding channel is open at a lateral end, wherein the escape prevention structure is formed at the lateral end by a barrier structure for reducing a cross-section of the bonding channel at the lateral end.

Claim 5. (previously presented) The arrangement of claim 4, wherein the barrier structure is connected to the interconnect layer.

Claim 6. (previously presented) The arrangement of claim 4, wherein the barrier structure is formed integrally with the interconnect layer.

Claim 7. (previously presented) The arrangement of claim 4, wherein the barrier structure extends across the entire width of the bonding channel.

Claim 8. (previously presented) The arrangement of claim 4, wherein the barrier structure is formed, so that a cross-section of the bonding channel tapers in a direction to the lateral end.

Claim 9. (previously presented) The arrangement of claim 4, wherein the barrier structure has a convex shape.

Claim 10. (previously presented) The arrangement of claim 4, wherein the barrier structure is disposed in the bonding channel and spaced from the interconnect layer.

Claim 11. (previously presented) The arrangement of claim 1, wherein the escape prevention structure includes a recess in the supporting substrate.

Claim 12. (canceled)

Claim 13. (previously presented) The arrangement of claim 11, wherein the interconnect layer is disposed on a surface of the supporting substrate, wherein the recess on the surface extends across a sidewall of the bonding channel.

Claim 14. (previously presented) The arrangement of claim 11, wherein the recess is disposed in a region of the bonding channel, wherein the recess extends from a first surface of the supporting substrate to a second surface of the supporting substrate.

Claims 15-22. (canceled)

Claim 23. (currently amended) An arrangement for use in a package, comprising:

a supporting substrate with a bond opening therein;

an interconnect layer disposed on the supporting substrate;

a bonding channel overlapping with the bond opening disposed in the interconnect

layer, said bond opening and bonding channel configured to receive at least one bond wire;

a chip fixedly secured to the interconnect layer and substantially covering the bonding channel;

an encapsulation material arranged in the bonding channel; and

an escape prevention structure disposed between the chip and the supporting substrate, the escape prevention structure configured to substantially prevent an encapsulation material flow out of the bonding channel, and further configured to enable escaping of air from the bonding channel.

Claim 24. (previously presented) The arrangement of claim 23, wherein the bonding channel has an opening at a lateral end, and wherein the escape prevention structure defines the cross section of the opening of the bonding channel.

Claim 25. (previously presented) The arrangement of claim 24, wherein the escape prevention structure includes a portion connected to the interconnect layer.

Claim 26. (previously presented) The arrangement of claim 24, wherein the escape prevention structure includes a portion formed integrally with the interconnect layer.

Claim 27. (previously presented) The arrangement of claim 24, wherein the escape prevention structure includes a portion that extends across the entire width of the bonding channel.

Claim 28. (previously presented) The arrangement of claim 24, wherein the escape prevention structure is formed such that a cross-section of the bonding channel tapers in a direction to the lateral end.

Claim 29. (previously presented) The arrangement of claim 24, wherein the escape prevention structure has a convex shape.

Claim 30. (previously presented) The arrangement of claim 24, wherein the escape prevention structure is disposed in the bonding channel and spaced from the interconnect layer.

Claim 31. (previously presented) The arrangement of claim 24, wherein the escape prevention structure includes a recess in the supporting substrate.